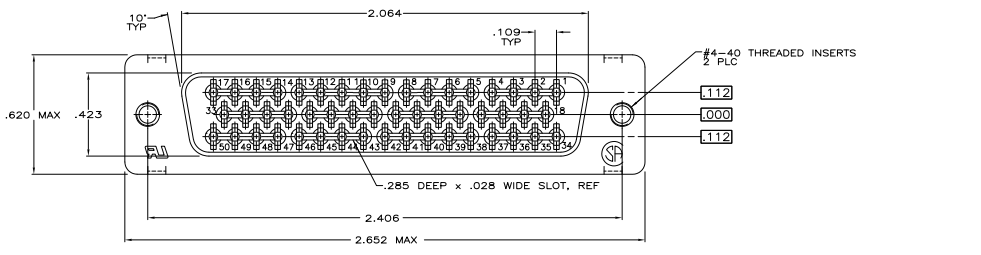
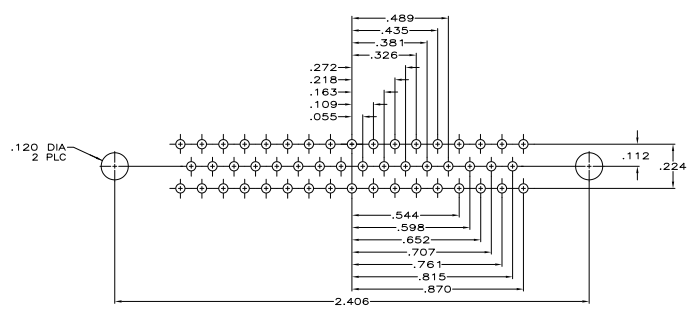
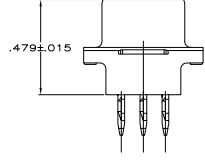
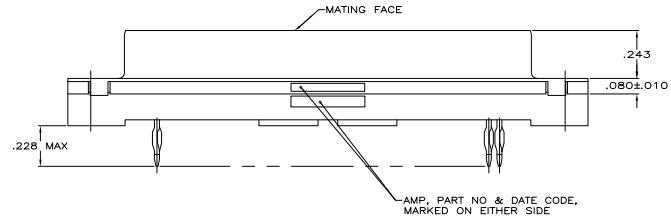


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REV	DATE	DESCRIPTION	BY	APP
00				
01		REVISED FOR ECO-10-01864		



- PC BOARD RECOMMENDATIONS:
- A. HOLES SHOULD BE DRILLED WITH A 1.15 mm DRILL.
  - B. MINIMUM PCB TIN/LEAD PLATING TO BE .0003 THICK OVER .002±1.001 THICK COPPER.
  - C. RECOMMENDED HOLE SIZE AFTER TIN/LEAD PLATING IS .037 TO .043 FOR POS .093 TO .125 THICK.
  - D. IF HOLE IS REFLOWED AFTER PLATING, DIA TO BE .036 TO .043.
- △ DUPLEX PLATED; GOLD FLASH ON MATING SURFACE, BRIGHT TIN OR BRIGHT TIN LEAD ON COMPLIANT PIN, ALL OVER NICKEL.
- △ 0.76 MICRO METERS [.000030] MINIMUM GOLD IN MATING AREA.  
 2.54 MICRO METERS [.000100] MINIMUM TIN OR TIN-LEAD ON COMPLIANT PIN.  
 ALL OVER 1.27 MICRO METERS [.000050] MINIMUM NICKEL.  
 OR  
 GOLD FLASH OVER PALLADIUM NICKEL.  
 0.76 MICRO METERS [.000030] MINIMUM TOTAL IN MATING AREA.  
 2.54 MICRO METERS [.000100] MINIMUM TIN OR TIN-LEAD ON COMPLIANT PIN.  
 ALL OVER 1.27 MICRO METERS [.000050] MINIMUM NICKEL.
- △ PLATED .0002-.0004 BRIGHT TIN
5. CONNECTOR MATES WITH ANY SIZE 5, 50 POSITION PLUG IN AMPLIMITE SERIES & COMPLIES WITH AMP SPEC 108-40014 WHERE APPLICABLE.



REVISION	DATE	DESCRIPTION	BY	APP
OBSOLETE	FULL	△		747144-3
OBSOLETE	HALF	△		747144-2
OBSOLETE	HALF	△		747144-1

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV	DATE	BY	APP
DESIGNER	DATE	04-12-01			
DESIGNED BY	DATE	04-28-01			
CHECKED BY	DATE				
APPROVED BY	DATE				
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